2.5V LVDS, 1:16 GLITCHLESS CLOCK BUFFER TERABUFFER™ II

IDT5T93GL161

General Description

The IDT5T93GL161 2.5V differential clock buffer is a user-selectable differential input to sixteen LVDS outputs. The fanout from a differential input to sixteen LVDS outputs reduces loading on the preceding driver and provides an efficient clock distribution network. The IDT5T93GL161 can act as a translator from a differential HSTL, eHSTL, LVEPECL (2.5V), LVPECL (3.3V), CML, or LVDS input to LVDS outputs. A single-ended 3.3V / 2.5V LVTTL input can also be used to translate to LVDS outputs. The redundant input capability allows for a glitchless change-over from a primary clock source to a secondary clock source. Selectable inputs are controlled by SEL. During the switchover, the output will disable LOW for up to three clock cycles of the previously-selected input clock. The outputs will remain LOW for up to three clock cycles of the newly-selected clock, after which the outputs will start from the newly-selected input. A FSEL pin has been implemented to control the switchover in cases where a clock source is absent or is driven to DC levels below the minimum specifications.

The IDT5T93GL161 outputs can be asynchronously enabled/disabled. When disabled, the outputs will drive to the value selected by the GL pin. Multiple power and grounds reduce noise.

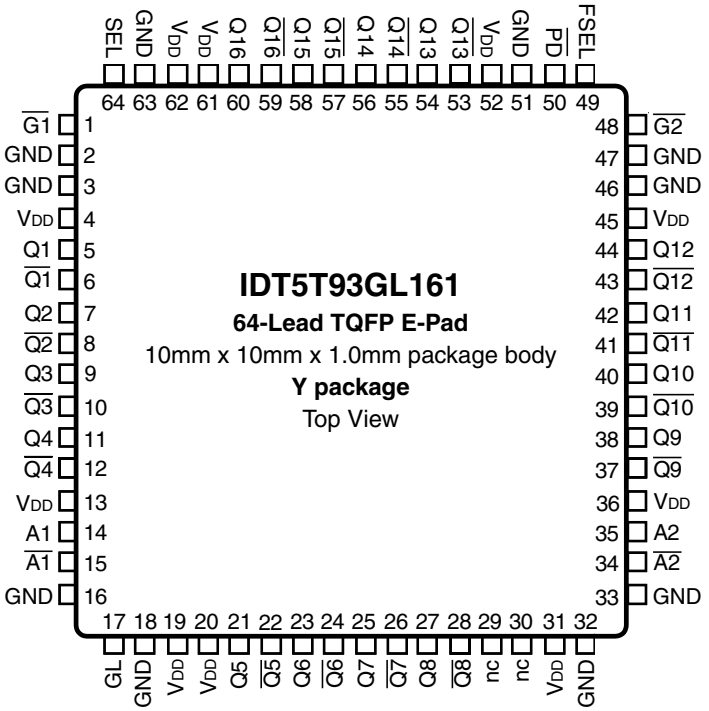
Features

- Guaranteed low skew: <75ps (maximum)
- Very low duty cycle distortion: <100ps (maximum)
- High speed propagation delay: <2.2ns (maximum)
- Up to 450MHz operation
- Selectable inputs
- Hot insertable and over-voltage tolerant inputs
- 3.3V/2.5V LVTTL, HSTL, eHSTL, LVEPECL (2.5V), LVPECL (3.3V), CML or LVDS input interface
- Selectable differential inputs to sixteen LVDS outputs
- Power-down mode
- At power-up, FSEL should be LOW
- 2.5V V_{DD}
- -40°C to 85°C ambient operating temperature
- Available in TQFP package

Applications

- Clock distribution

Pin Assignment



Block Diagram

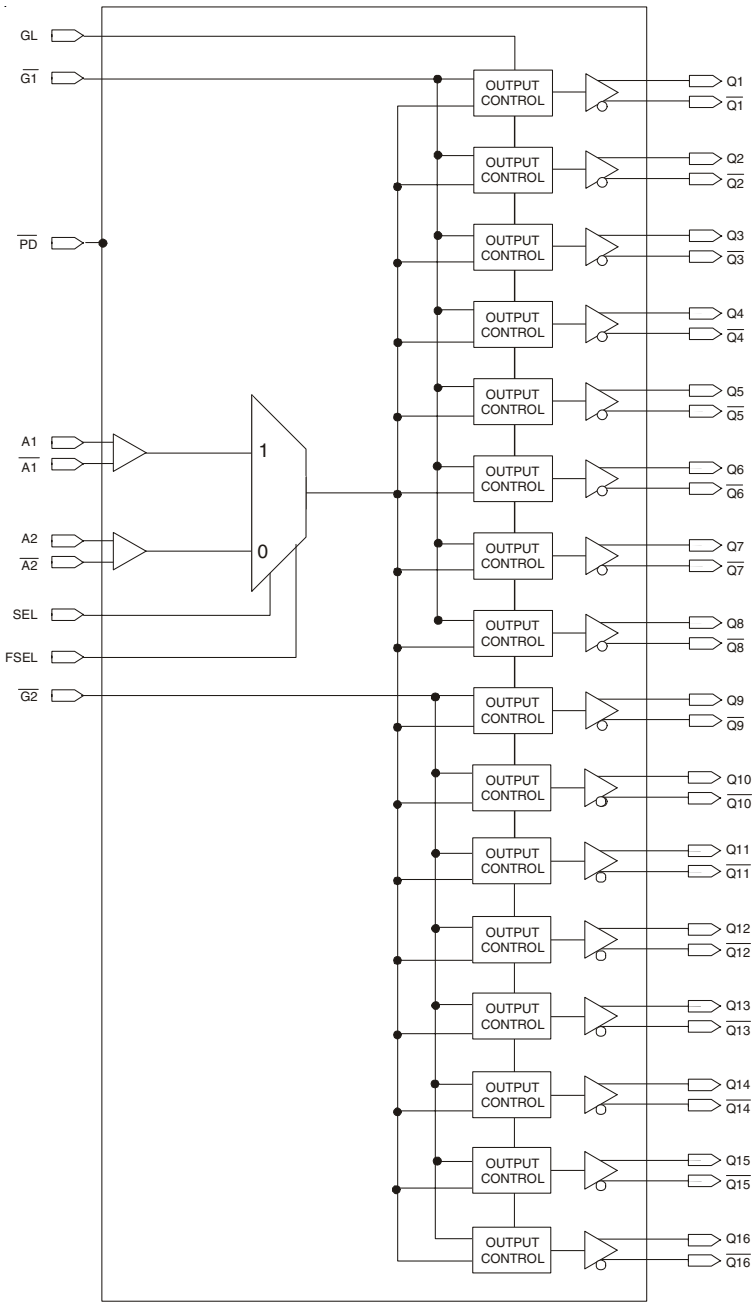


Table 1. Pin Descriptions

Name	Type		Description
A[1:2]	Input	Adjustable (1, 4)	Clock input. $A_{[1:2]}$ is the "true" side of the differential clock input.
$\overline{A[1:2]}$	Input	Adjustable (1, 4)	Complementary clock inputs. $\overline{A[1:2]}$ is the complementary side of A[1:2]. For LVTTL single-ended operation, $\overline{A[1:2]}$ should be set to the desired toggle voltage for A[1:2]: 3.3V LVTTL V_{REF} = 1650mV 2.5V LVTTL V_{REF} = 1250mV
$\overline{G1}$	Input	LVTTL	Gate control for differential outputs Q1 and $\overline{Q1}$ through Q8 and $\overline{Q8}$. When $\overline{G1}$ is LOW, the differential outputs are active. When $\overline{G1}$ is HIGH, the differential outputs are asynchronously driven to the level designated by GL(2).
$\overline{G2}$	Input	LVTTL	Gate control for differential outputs Q9 and $\overline{Q9}$ through Q16 and $\overline{Q16}$. When $\overline{G2}$ is LOW, the differential outputs are active. When $\overline{G2}$ is HIGH, the differential outputs are asynchronously driven to the level designated by GL(2).
GL	Input	LVTTL	Specifies output disable level. If HIGH, "true" outputs disable HIGH and "complementary" outputs disable LOW. If LOW, "true" outputs disable LOW and "complementary" outputs disable HIGH.
Q[1:16]	Output	LVDS	Clock outputs.
$\overline{Q\{1:16\}}$	Output	LVDS	Complementary clock outputs.
SEL	Input	LVTTL	Reference clock select. When LOW, selects A2 and $\overline{A2}$. When HIGH, selects A1 and $\overline{A1}$.
$\overline{PD}$	Input	LVTTL	Power-down control. Shuts off entire chip. If LOW, the device goes into LOW power mode. Inputs and outputs are disabled. Both "true" and "complementary" outputs will pull to V_{DD}. Set HIGH for normal operation.(3)
FSEL	Input	LVTTL	At a rising edge, FSEL forces select to the input designated by SEL. Set LOW for normal operation. At power-up, FSEL should be LOW.
V_{DD}		Power	Power supply for the device core and inputs.
GND		Power	Ground.

NOTES:
1. Inputs are capable of translating the following interface standards:
   Single-ended 3.3V and 2.5V LVTTL levels
   Differential HSTL and eHSTL levels
   Differential LVEPECL (2.5V) and LVPECL (3.3V) levels
   Differential LVDS levels
   Differential CML levels
2. Because the gate controls are asynchronous, runt pulses are possible. It is the user's responsibility to either time the gate control signals to minimize the possibility of runt pulses or be able to tolerate them in down stream circuitry.
3. It is recommended that the outputs be disabled before entering power-down mode. It is also recommended that the outputs remain disabled until the device completes power-up after asserting $\overline{PD}$.
4. The user must take precautions with any differential input interface standard being used in order to prevent instability when there is no input signal.

Table 2. Pin Characteristics (T_A = +25°C, F = 1.0MHz)

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance				3	pF

NOTE: This parameter is measured at characterization but not tested.

Function Tables

Table 3A. Gate Control Output Table

Control Outputs		Outputs	
GL	**$\overline{G}$**	**Q[1:16]**	**$\overline{Q[1:16]}$**
0	0	Toggling	Toggling
0	1	LOW	HIGH
1	0	Toggling	Toggling
1	1	HIGH	LOW

Table 3B. Input Selection Table

Selection SEL pin	Inputs
0	A2/$\overline{A2}$
1	A1/$\overline{A1}$

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Power Supply Voltage, V_{DD}	-0.5V to +3.6V
Input Voltage, V_I	-0.5V to +3.6V
Output Voltage, V_O Not to exceed 3.6V	-0.5 to V_{DD} +0.5V
Storage Temperature, T_{STG}	-65°C to +150°C
Junction Temperature, T_J	150°C

Recommended Operating Range

Symbol	Description	Minimum	Typical	Maximum	Units
T_A	Ambient Operating Temperature	-40	+25	+85	°C
V_{DD}	Internal Power Supply Voltage	2.3	2.5	2.7	V

DC Electrical Characteristics

Table 4A. LVDS Power Supply DC Characteristics(1), T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical(2)	Maximum	Units
I_{DDQ}	Quiescent V_{DD} Power Supply Current	V_{DD} = Max., All Input Clocks = LOW(2); Outputs enabled			350	mA
I_{TOT}	Total Power V_{DD} Supply Current	V_{DD} = 2.7V; $F_{REFERENCE}$ Clock = 450MHz			360	mA
I_{PD}	Total Power Down Supply Current	$\overline{PD}$ = LOW			5	mA

NOTE 1: These power consumption characteristics are for all the valid input interfaces and cover the worst case conditions.
NOTE 2: The true input is held LOW and the complementary input is held HIGH.

Table 4B. LVTTL DC Characteristics[1], T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical[2]	Maximum	Units
I_{IH}	Input High Current	V_{DD} = 2.7V			±5	µA
I_{IL}	Input Low Current	V_{DD} = 2.7V			±5	µA
V_{IK}	Clamp Diode Voltage	V_{DD} = 2.3V, I_{IN} = -18mA		-0.7	-1.2	V
V_{IN}	DC Input Voltage		-0.3		3.6	V
V_{IH}	DC Input High Voltage		1.7			V
V_{IL}	DC Input Low Voltage				0.7	V
V_{THI}	DC Input Threshold Crossing Voltage			V_{DD}/2		V
V_{REF}	Single-Ended Reference Voltage [3]	3.3V LVTTL		1.65		V
		2.5V LVTTL		1.25		V

NOTE 1: See *Recommended Operating Range* table.
NOTE 2: Typical values are at V_{DD} = 2.5V, +25°C ambient.
NOTE 3: For A[1:2] single-ended operation, $\overline{A}$[1:2] is tied to a DC reference voltage.

Table 4C. Differential DC Characteristics[1], T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical[2]	Maximum	Units
I_{IH}	Input High Current	V_{DD} = = 2.7V			±5	µA
I_{IL}	Input Low Current	V_{DD} = = 2.7V			±5	µA
V_{IK}	Clamp Diode Voltage	V_{DD} = 2.3V, I_{IN} = -18mA		-0.7	-1.2	V
V_{IN}	DC Input Voltage		-0.3		3.6	V
V_{DIF}	DC Differential Voltage[3]		0.1			V
V_{CM}	DC Common Mode Input Voltage		0.05		V_{DD}	V

NOTE 1: See *Recommended Operating Range* table.
NOTE 2: V_{DIF} specifies the minimum input differential voltage (V_{TR} - V_{CP}) required for switching where V_{TR} is the "true" input level and V_{CP} is the "complement" input level. The DC differential voltage must be maintained to guarantee retaining the existing HIGH or LOW input. The AC differential voltage must be achieved to guarantee switching to a new state.
NOTE 3: V_{CM} specifies the maximum allowable range of (V_{TR} + V_{CP}) /2.
NOTE 4: Typical values are at V_{DD} = 2.5V, +25°C ambient.

Table 4D. LVDS DC Characteristics[1], T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical[2]	Maximum	Units
$V_{OT(+)}$	Differential Output Voltage for the True Binary State		247		454	mV
$V_{OT(-)}$	Differential Output Voltage for the False Binary State		247		454	mV
ΔV_{OT}	Change in V_{OT} Between Complementary Output States				50	mV
V_{OS}	Output Common Mode Voltage (Offset Voltage)		1.125	1.2	1.375	V
ΔV_{OS}	Change in V_{OS} Between Complementary Output States				50	mV
I_{OS}	Outputs Short Circuit Current	V_{OUT+} and V_{OUT-} = 0V		12	24	mA
I_{OSD}	Differential Outputs Short Circuit Current	$V_{OUT+} = V_{OUT-}$		6	12	mA

NOTE 1: See *Recommended Operating Range* table.
NOTE 2: Typical values are at V_{DD} = 2.5V, +25°C ambient.

AC Electrical Characteristics

Table 5A. HSTL Differential Input AC Characteristics, T_A = -40°C to 85°C

Symbol	Parameter	Value	Units
V_{DIF}	Input Signal Swing[1]	1	V
V_X	Differential Input Signal Crossing Point[2]	750	mV
D_H	Duty Cycle	50	%
V_{THI}	Input Timing Measurement Reference Level[3]	Crossing Point	V
t_R / t_F	Input Signal Edge Rate[4]	2	V/ns

NOTE 1.The 1V peak-to-peak input pulse level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VDIF (AC) specification under actual use conditions.
NOTE 2.A 750mV crossing point level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VX specification under actual use conditions.
NOTE 3.In all cases, input waveform timing is marked at the differential cross-point of the input signals.
NOTE 4.The input signal edge rate of 2V/ns or greater is to be maintained in the 20% to 80% range of the input waveform.

Table 5B. eHSTL AC Differential Input Characteristics, T_A = -40°C to 85°C

Symbol	Parameter	Value	Units
V_{DIF}	Input Signal Swing(1)	1	V
V_X	Differential Input Signal Crossing Point(2)	900	mV
D_H	Duty Cycle	50	%
V_{THI}	Input Timing Measurement Reference Level(3)	Crossing Point	V
t_R / t_F	Input Signal Edge Rate(4)	2	V/ns

NOTE 1.The 1V peak-to-peak input pulse level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VDIF (AC) specification under actual use conditions.
NOTE 2.A 900mV crossing point level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VX specification under actual use conditions.
NOTE 3.In all cases, input waveform timing is marked at the differential cross-point of the input signals.
NOTE 4.The input signal edge rate of 2V/ns or greater is to be maintained in the 20% to 80% range of the input waveform.

Table 5C. LVEPECL (2.5V) and LVPECL (3.3V) Differential Input AC Characteristics, T_A = -40°C to 85°C

Symbol	Parameter		Maximum	Units
V_{DIF}	Input Signal Swing(1)		732	mV
V_X	Differential Input Cross Point Voltage(2)	LVEPECL	1082	mV
		LVPECL	1880	m
D_H	Duty Cycle		50	%
V_{THI}	Input Timing Measurement Reference Level(3)		Crossing Point	V
t_R / t_F	Input Signal Edge Rate(4)		2	V/ns

NOTE 1.The 732mV peak-to-peak input pulse level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VDIF (AC) specification under actual use conditions.
NOTE 2.A 1082mV LVEPECL (2.5V) and 1880mV LVPECL (3.3V) crossing point level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VX specification under actual use conditions.
NOTE 3.In all cases, input waveform timing is marked at the differential cross-point of the input signals.
NOTE 4.The input signal edge rate of 2V/ns or greater is to be maintained in the 20% to 80% range of the input waveform.

Table 5D. LVDS Differential Input AC Characteristics, T_A = -40°C to 85°C

Symbol	Parameter	Maximum	Units
V_{DIF}	Input Signal Swing(1)	400	mV
V_X	Differential Input Cross Point Voltage(2)	1.2	V
D_H	Duty Cycle	50	%
V_{THI}	Input Timing Measurement Reference Level(3)	Crossing Point	V
t_R / t_F	Input Signal Edge Rate(4)	2	V/ns

NOTE 1.The 400mV peak-to-peak input pulse level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VDIF (AC) specification under actual use conditions.
NOTE 2.A 1.2V crossing point level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VX specification under actual use conditions.
NOTE 3.In all cases, input waveform timing is marked at the differential cross-point of the input signals.
NOTE 4.The input signal edge rate of 2V/ns or greater is to be maintained in the 20% to 80% range of the input waveform.

Table 5E. AC Differential Input Characteristics(1), T_A = -40°C to 85°C

Symbol	Parameter	Minimum	Typical	Maximum	Units
V_{DIF}	AC Differential Voltage(2)	0.1		3.6	V
V_{IX}	Differential Input Cross Point Voltage	0.05		V_{DD}	V
V_{CM}	Common Mode Input Voltage Range(3)	0.05		V_{DD}	V
V_{IN}	Input Voltage	-0.3		3.6	V

NOTE 1.The output will not change state until the inputs have crossed and the minimum differential voltage range defined by V_{DIF} has been met or exceeded.
NOTE 2.V_{DIF} specifies the minimum input voltage ($V_{TR} – V_{CP}$) required for switching where V_{TR} is the “true” input level and V_{CP} is the “complement” input level. The AC differential voltage must be achieved to guarantee switching to a new state.
NOTE 3.IV_{CM} specified the maximum allowable range of ($V_{TR} + V_{CP}$) /2.

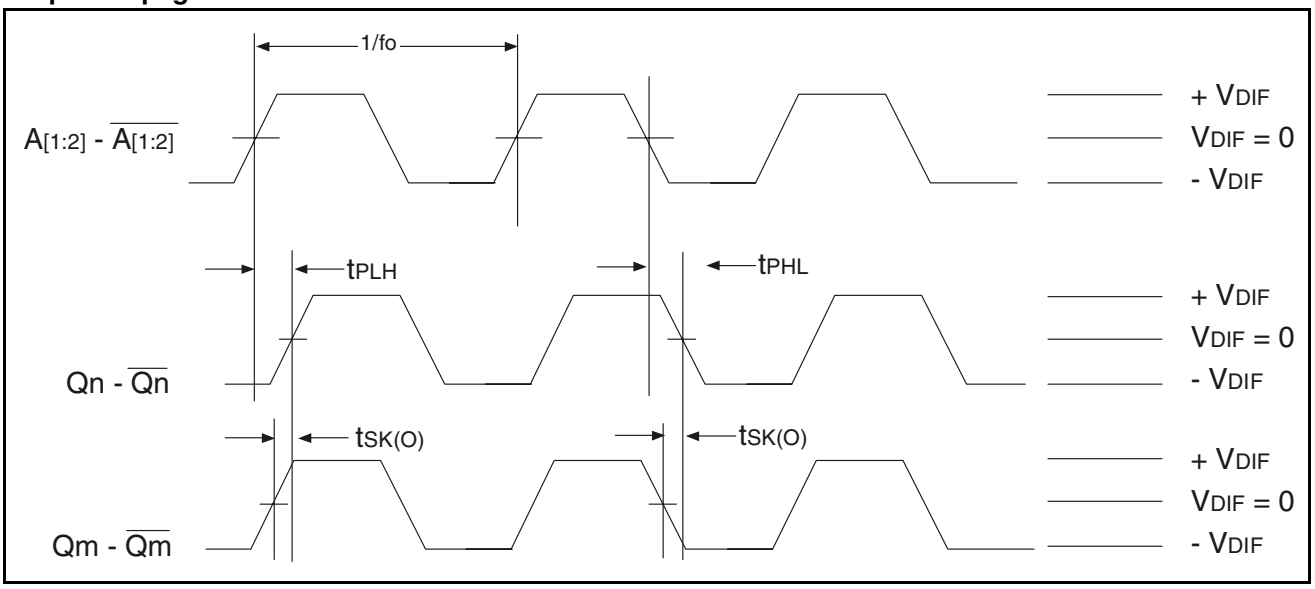
Table 5F. AC Characteristics(1,5), T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
*t*sk(o)	Same Device Output Pin-to-Pin Skew (2)				75	ps
*t*sk(p)	Pulse Skew(3)				100	ps
*t*sk(pp)	Part-to-Part Skew(4)				300	ps
tp_{LH}	Propagation Delay, Low-to-High	A/$\overline{A}$ Crosspoint to Qn/$\overline{Qn}$ Crosspoint		1.5	2.2	ns
tp_{HL}	Propagation Delay, High-to-Low			1.5	2.2	ns
fo	Frequency Range(6)				450	MHz
t_{PGE}	Output Gate Enable Crossing V_{THI}-to-Qn/$\overline{Qn}$ Crosspoint				3.5	ns
t_{PGD}	Output Gate Disable Crossing V_{THI}-to-Qn/$\overline{Qn}$ Crosspoint Driven to GL Designated Level				3.5	ns
t_{PWRDN}	$\overline{PD}$ Crossing V_{THI}-to-Qn = V_{DD}, $\overline{Qn}$ = V_{DD}				100	µS
t_{PWRUP}	Output Gate Disable Crossing V_{THI} to Qn/$\overline{Qn}$ Driven to GL Designated Level				100	µS

NOTE 1. AC propagation measurements should not be taken within the first 100 cycles of startup.
NOTE 2. Skew measured between crosspoints of all differential output pairs under identical input and output interfaces, transitions and load conditions on any one device.
NOTE 3. Skew measured is the difference between propagation delay times tp_{HL} and tp_{LH} of any single differential output pair under identical input and output interfaces, transitions and load conditions on any one device.
NOTE 4. Skew measured is the magnitude of the difference in propagation times between any single differential output pair of two devices, given identical transitions and load conditions at identical V_{DD} levels and temperature.
NOTE 5. All parameters are tested with a 50% input duty cycle.
NOTE 6. Guaranteed by design but not production tested.

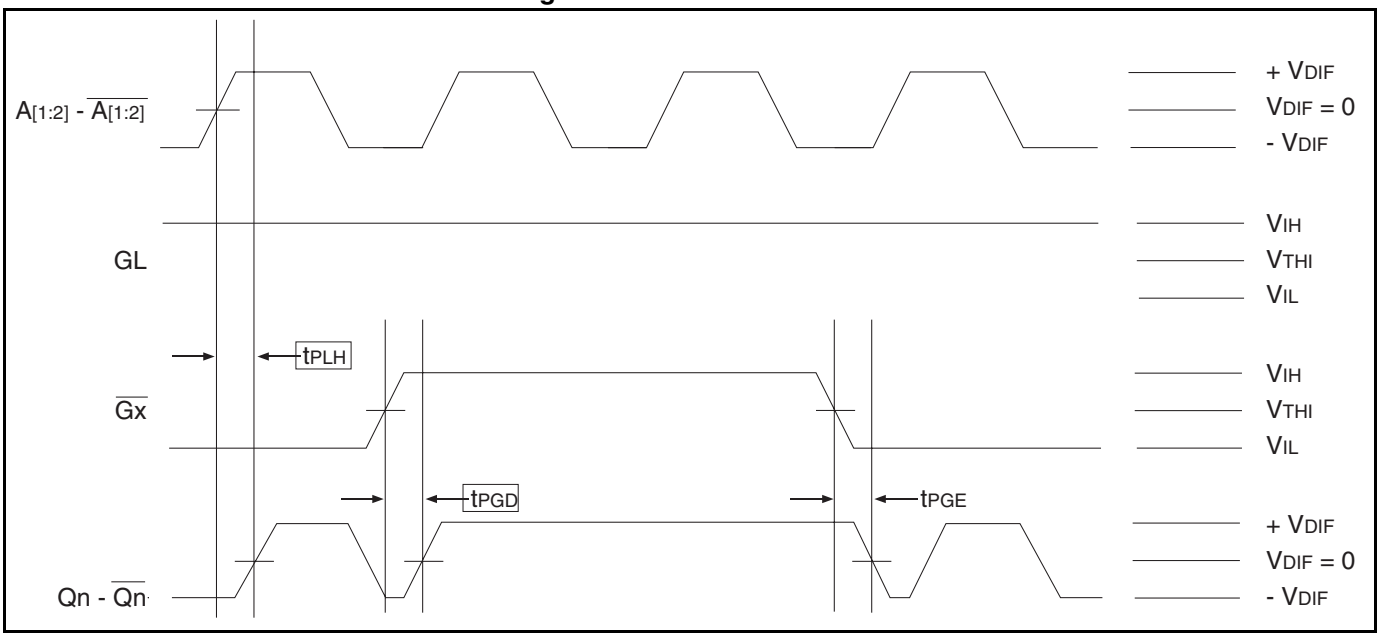
Differential AC Timing Waveforms

Output Propagation and Skew Waveforms



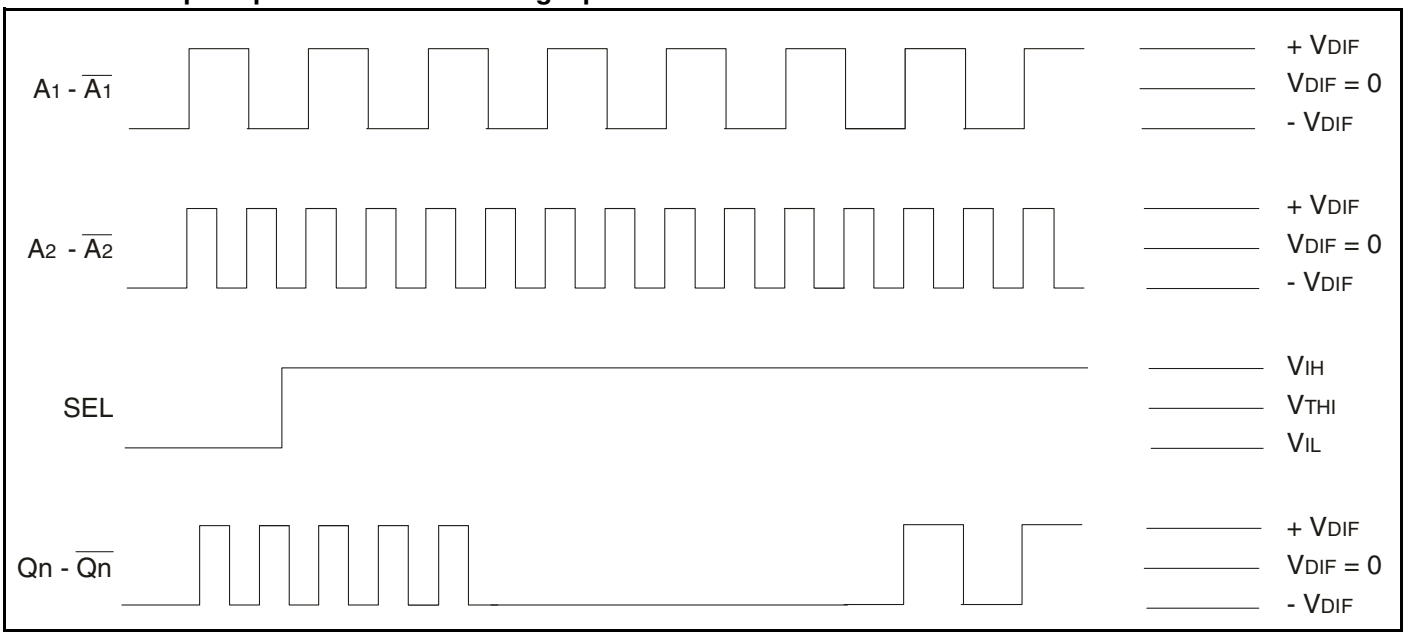
NOTE 1: Pulse skew is calculated using the following expression:
$tsk(p) = |tp_{HL} - tp_{LH}|$
Note that the tp_{HL} and tp_{LH} shown above are not valid measurements for this calculation because they are not taken from the same pulse.
NOTE 2: AC propagation measurements should not be taken within the first 100 cycles of startup.

Differential Gate Disabled/Endable Showing Runt Pulse Generation



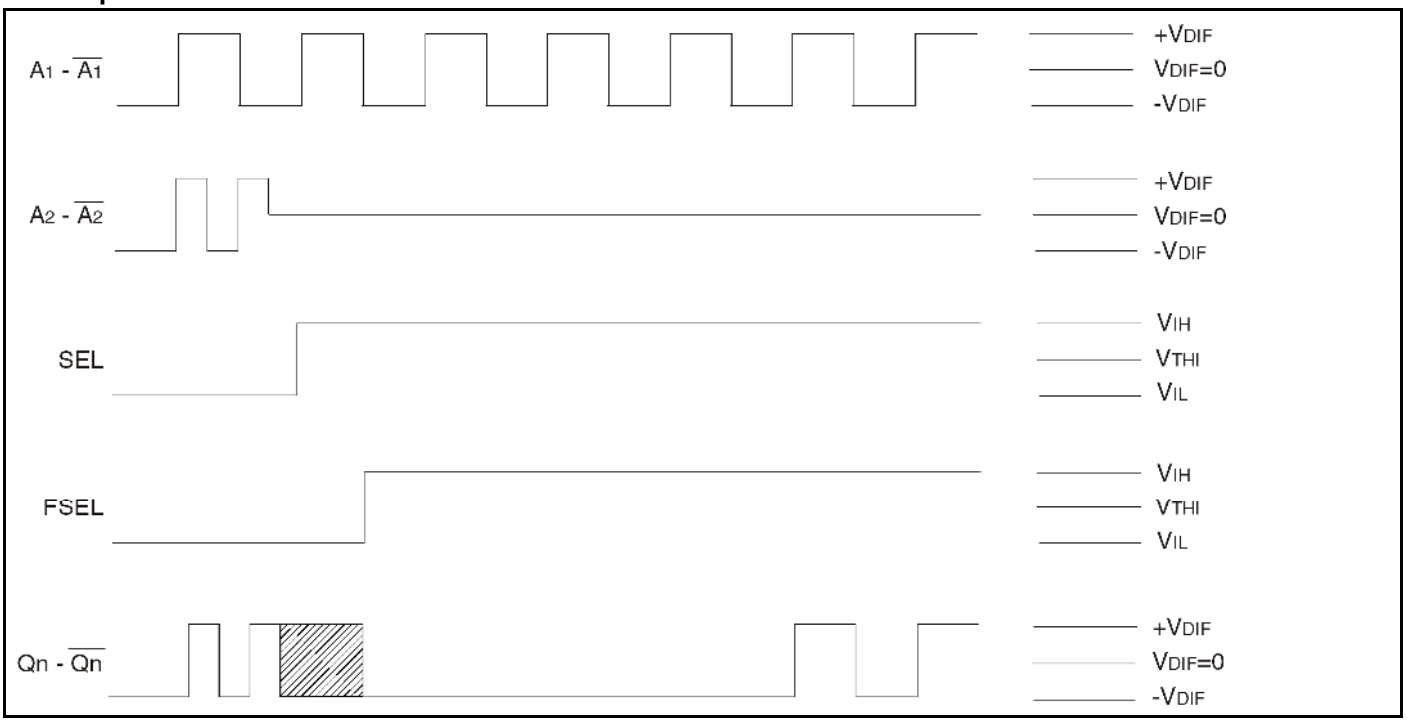
NOTE 1: As shown, it is possible to generate runt pulses on gate disable and enable of the outputs. It is the user's responsibility to time the $\overline{G}$ signal to avoid this problem.

Glitchless Output Operation with Switching Input Clock Selection



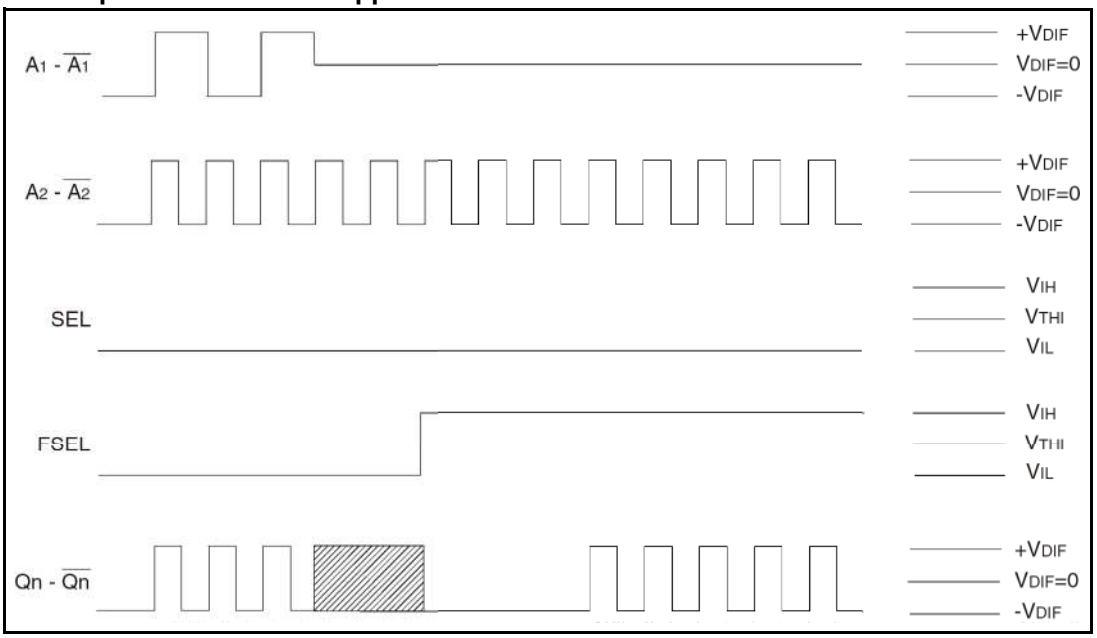
1. When SEL changes, the output clock goes LOW on the falling edge of the output clock up to three cycles later. The output then stays LOW for up to three clock cycles of the new input clock. After this, the output starts with the rising edge of the new input clock.
2. AC propagation measurements should not be taken within the first 100 cycles of startup.

FSEL Operation for When Current Clock Dies



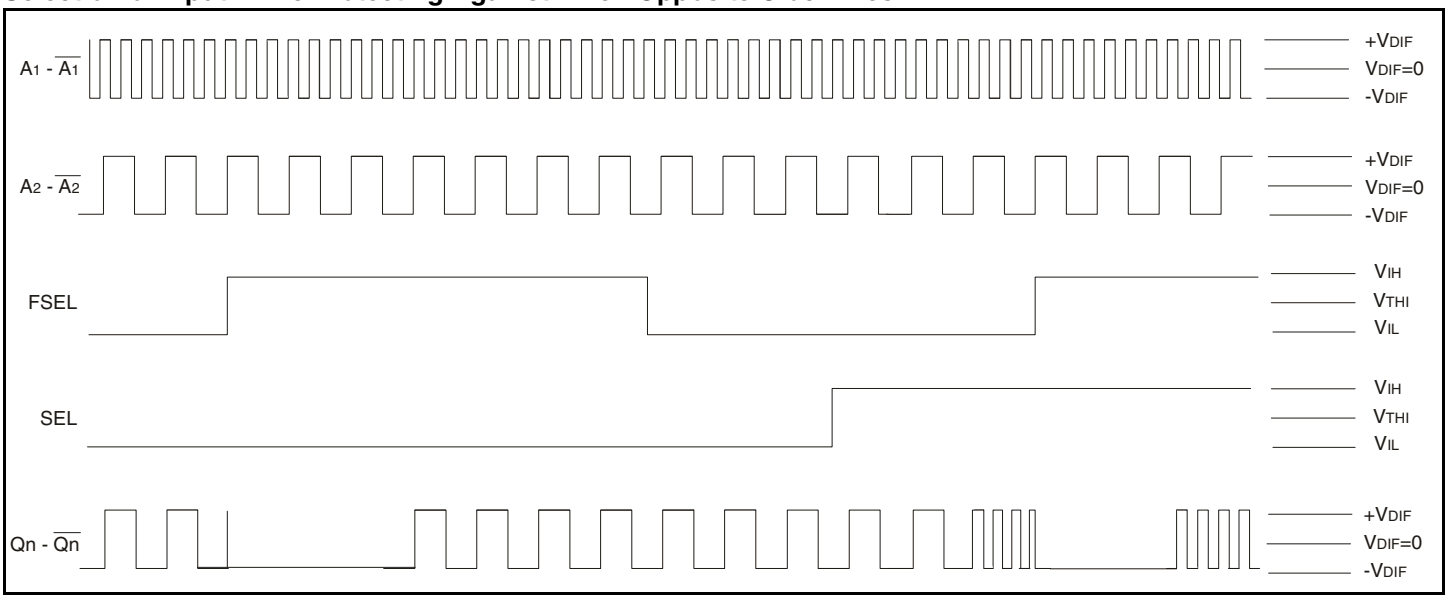
1. When the differential on the selected clock goes below the minimum DC differential, the outputs clock goes to an unknown state. When this happens, the SEL pin should be toggled and FSEL asserted in order to force selection of the new input clock. The output clock will start up after a number of cycles of the newly-selected input clock.
2. The FSEL pin should stay asserted until the problem with the dead clock can be fixed in the system.
3. It is recommended that the FSEL be tied HIGH for systems that use only one input. If this is not possible, the user must guarantee that the unused input have a differential greater than or equal to the minimum DC differential specified in the datasheet.

FSEL Operation for When Opposite Clock Dies



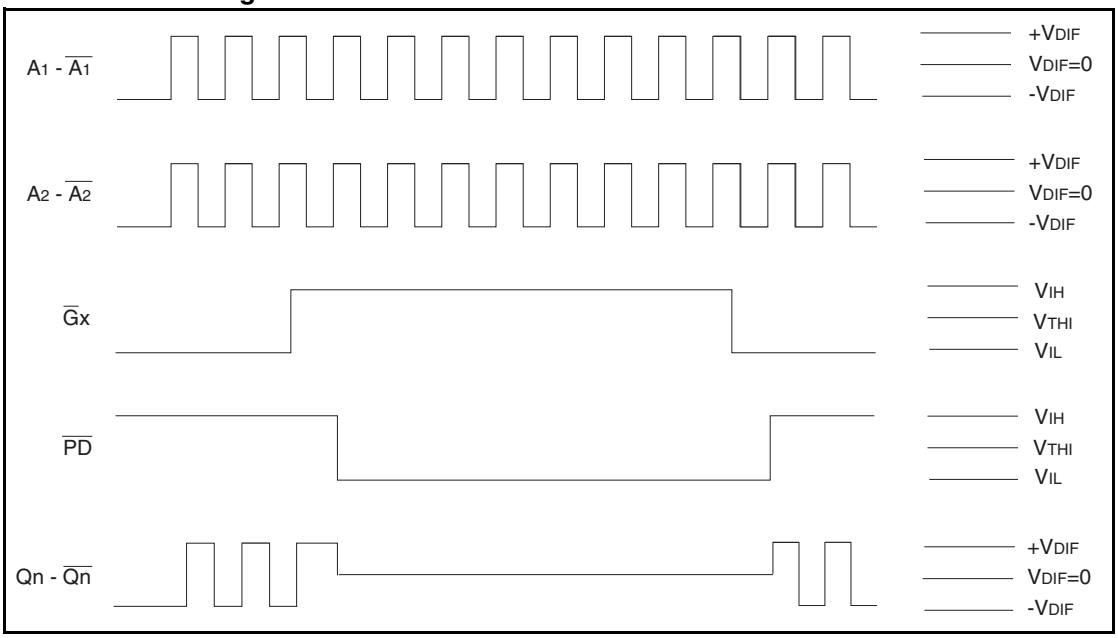
1. When the differential on the non-selected clock goes below the minimum DC differential, the outputs clock goes to an unknown state. When this happens, the FSEL pin should be asserted in order to force selection of the new input clock. The output clock will start up after a number of cycles of the newly-selected input clock.
2. The FSEL pin should stay asserted until the problem with the dead clock can be fixed in the system.
3. It is recommended that the FSEL be tied HIGH for systems that use only one input. If this is not possible, the user must guarantee that the unused input have a differential greater than or equal to the minimum DC differential specified in the datasheet.

Selection of Input While Protecting Against When Opposite Clock Dies



1. If the user holds FSEL HIGH, the output will not be affected by the deselected input clock.
2. The output will immediately be driven to LOW once FSEL is asserted. This may cause glitching on the output. The output will restart with the input clock selected by the SEL pin.
3. If the user decides to switch input clocks, the user must de-assert FSEL, then assert FSEL after toggling the SEL input pin. The output will be driven LOW and will restart with the input clock selected by the SEL pin.

Power Down Timing



NOTE 1: It is recommended that outputs be disabled before entering power-down mode. It is also recommended that the outputs remain disabled until the device completes power-up after asserting $\overline{PD}$.
NOTE 2: The *Power Down Timing* diagram assumes that GL is HIGH.
NOTE 3: It should be noted that during power-down mode, the outputs are both pulled to V_{DD}. In the *Power Down Timing* diagram this is shown when Qn/$\overline{Qn}$ goes to V_{DIF} = 0.

Test Circuits and Conditions

Test Circuit for Differential Input

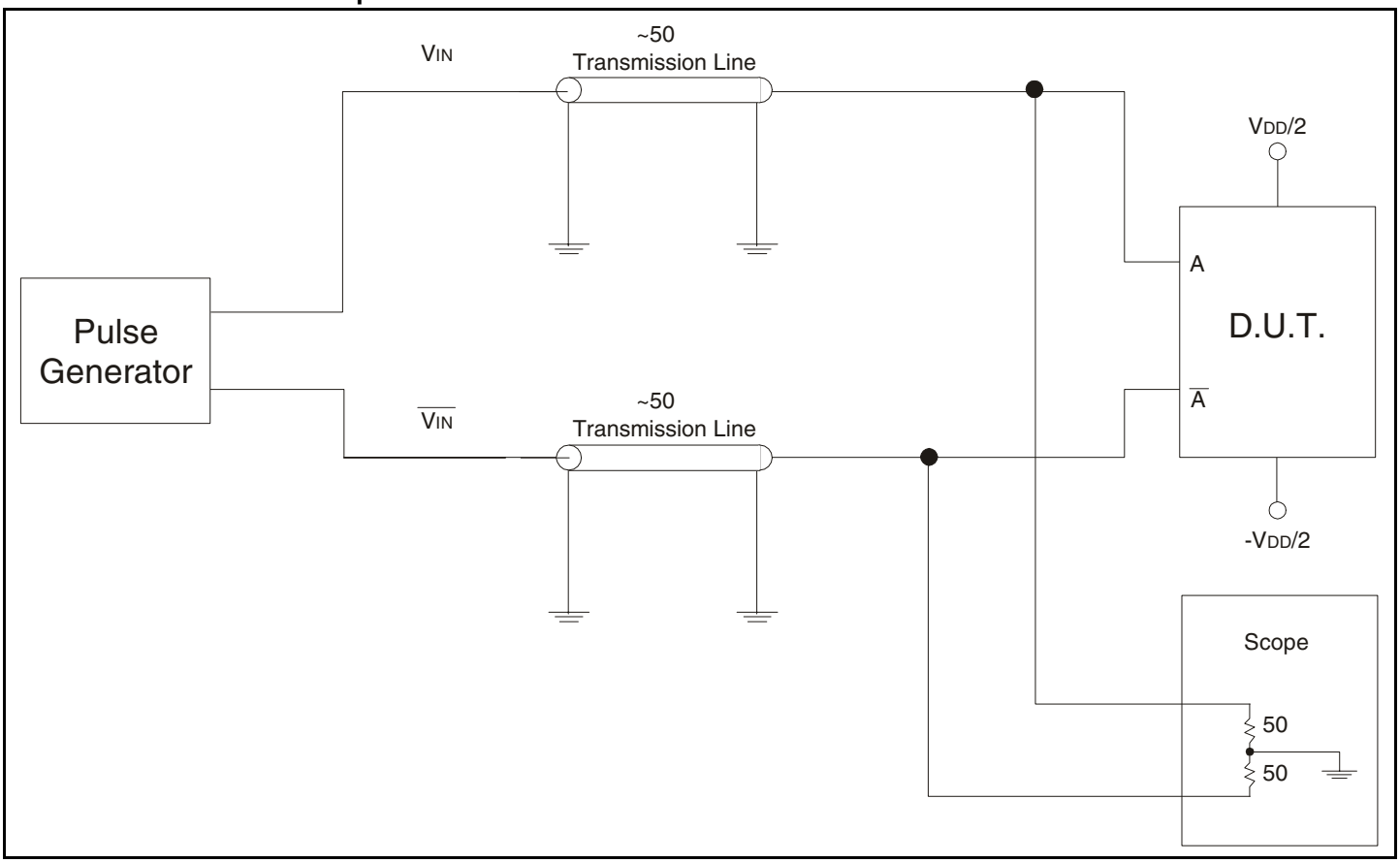
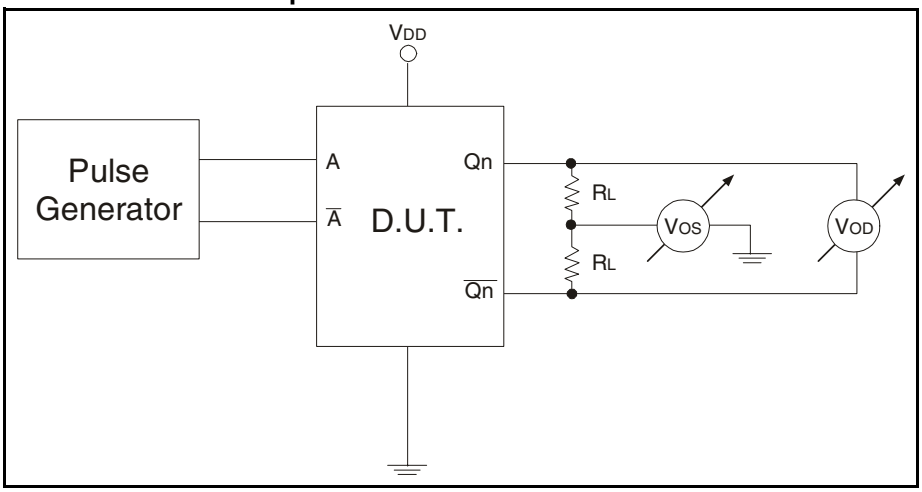


Table 6A. Differential Input Test Conditions

Symbol	V_{DD} = 2.5V ± 0.2V	Unit
V_{THI}	Crossing of A and $\overline{A}$	V

Test Circuit for DC Outputs and Power Down Tests



Test Circuit for Propagation, Skew, and Gate Enable/Disable Timing

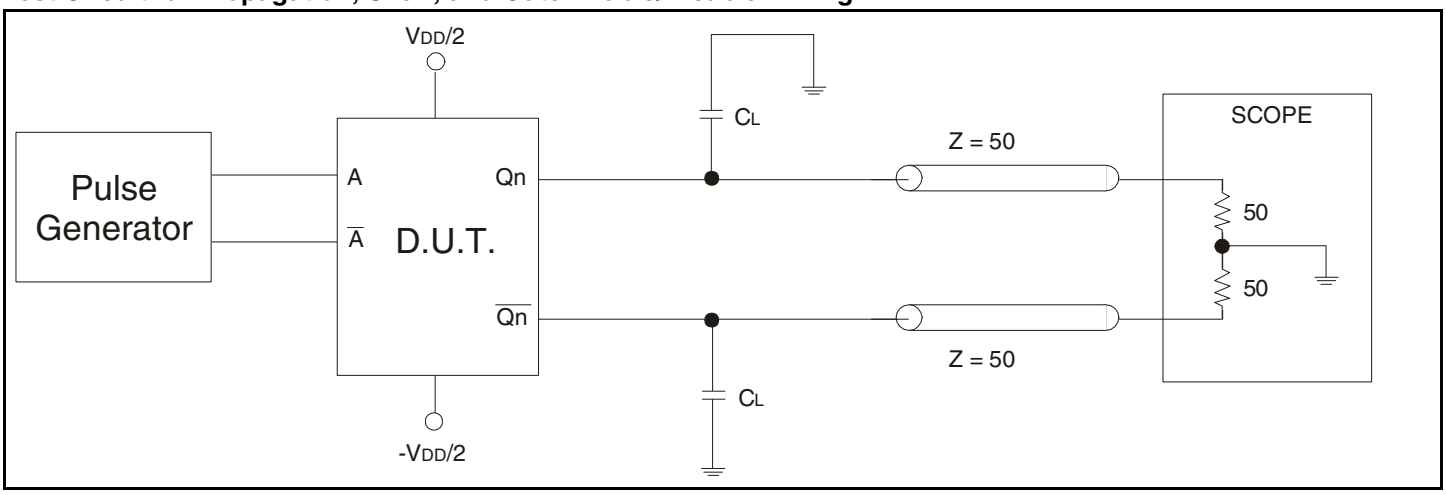
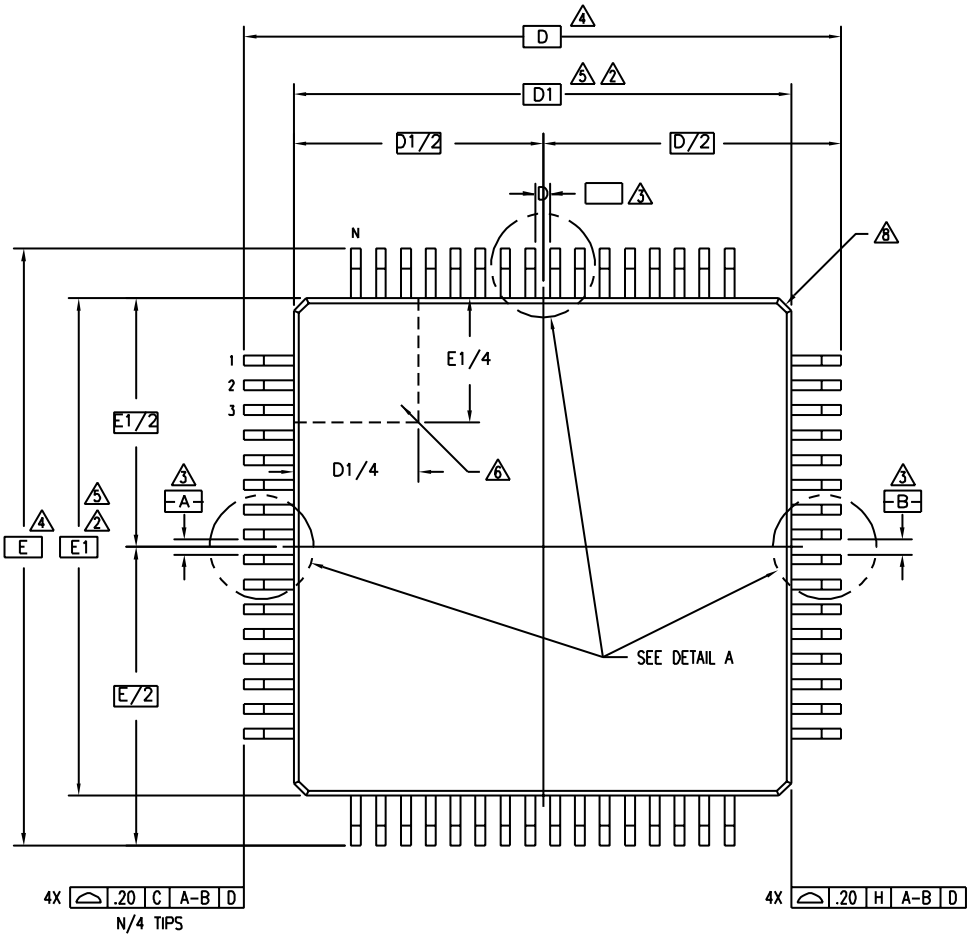


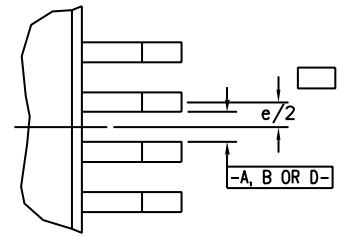
Table 6B. Differential Input Test Conditions

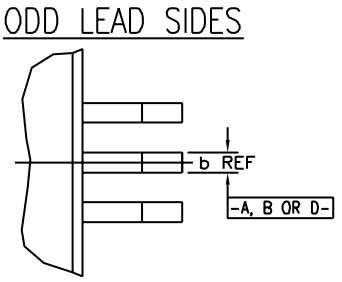
Symbol	V_{DD} = 2.5V ± 0.2V	Unit
C_L	0(1)	pF
	8(1,2)	pF
R_L	50	Ω

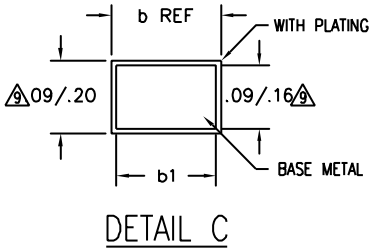
NOTE 1: Specifications only apply to "Normal Operations" test condition. The T_{IA}/E_{IA} specification load is for reference only.
NOTE 2: The scope inputs are assumed to have a 2pF load to ground. T_{IA}/E_{IA} – 644 specifies 5pF between the output pair. With C_L = 8pF, this gives the test circuit appropriate 5pF equivalent load.

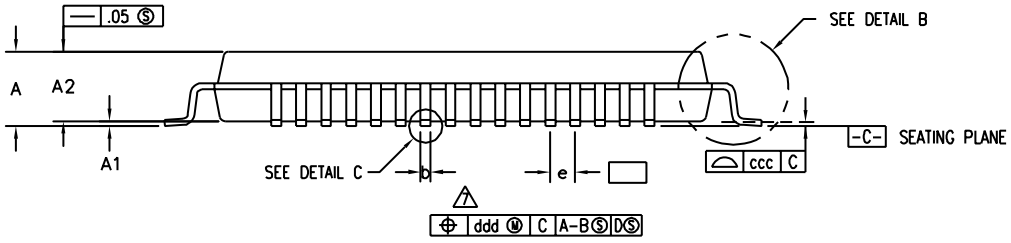
Package Outline

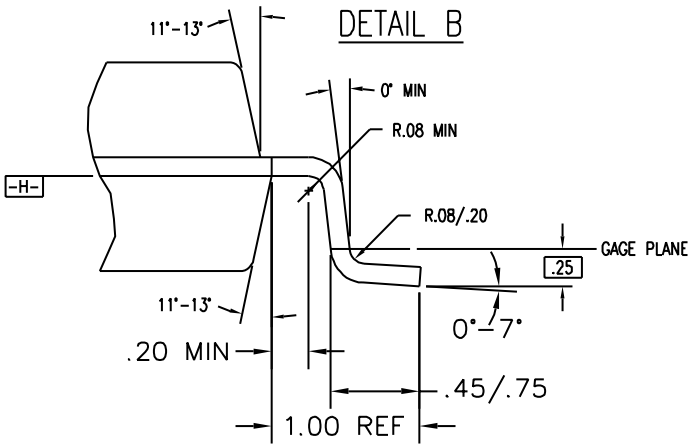












TOLERANCES UNLESS SPECIFIED		IDT™ www.IDT.com	2975 Stender Way Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674	
DECIMAL XX± XXX± XXXX±	ANGULAR ±			
APPROVALS	DATE	TITLE	PP/PPG PACKAGE OUTLINE 10.0 X 10.0 X 1.4 mm STQFP/TQFP 1.00/.10 FORM	
DRAWN JV	11/18/94			
CHECKED		SIZE C	DRAWING No. PSC-4046	REV 05
		DO NOT SCALE DRAWING		SHEET 1 OF 2

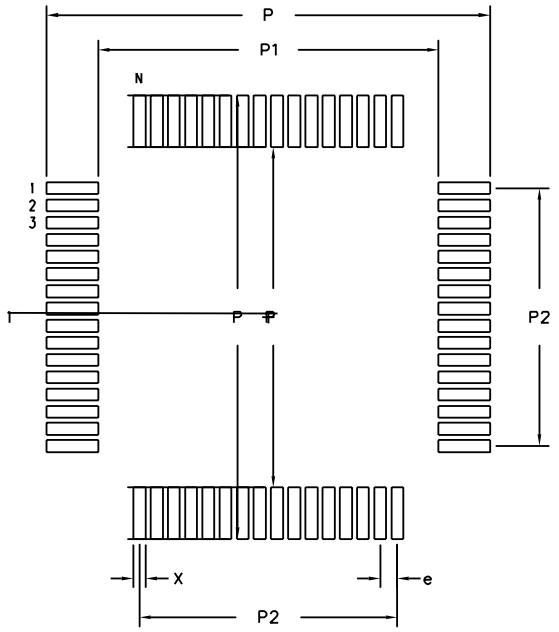
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
	01	ADDED TABLE FOR 44-PIN	07/05/00	T. VU
	02	CORRECTED P & P1 DIMENSIONS	07/05/00	T. VU
	03	SWAPPED P & P1 DIMENSIONS	08/09/01	D.XUE
	04	ADD STQFP IN THE TITLE BLOCK	08/31/01	
	05	ADD "GREEN" PPG NOMENCLATURE	10/13/04	TU VU

Package Dimensions

SYMBOL	JEDEC VARIATION BJ			NOTE
	MIN	NOM	MAX	
A	–	–	1.60	
A1	.05	.10	.15	
A2	1.35	1.40	1.45	
D	12.00 BSC			4
D1	10.00 BSC			5,2
E	12.00 BSC			4
E1	10.00 BSC			5,2
N	64			
e	.50 BSC			
b	.17	.22	.27	7
b1	.17	.20	.23	
ccc	–	–	.08	
ddd	–	–	.08	

	PP44		PP64	
	MIN	MAX	MIN	MAX
P	12.80	13.00	12.80	13.00
P1	9.80	10.00	9.80	10.00
P2	8.00 BSC		7.50 BSC	
X	.45	.60	.30	.40
e	.80 BSC		.50 BSC	
N	44		64	

LAND PATTERN DIMENSIONS



NOTES:

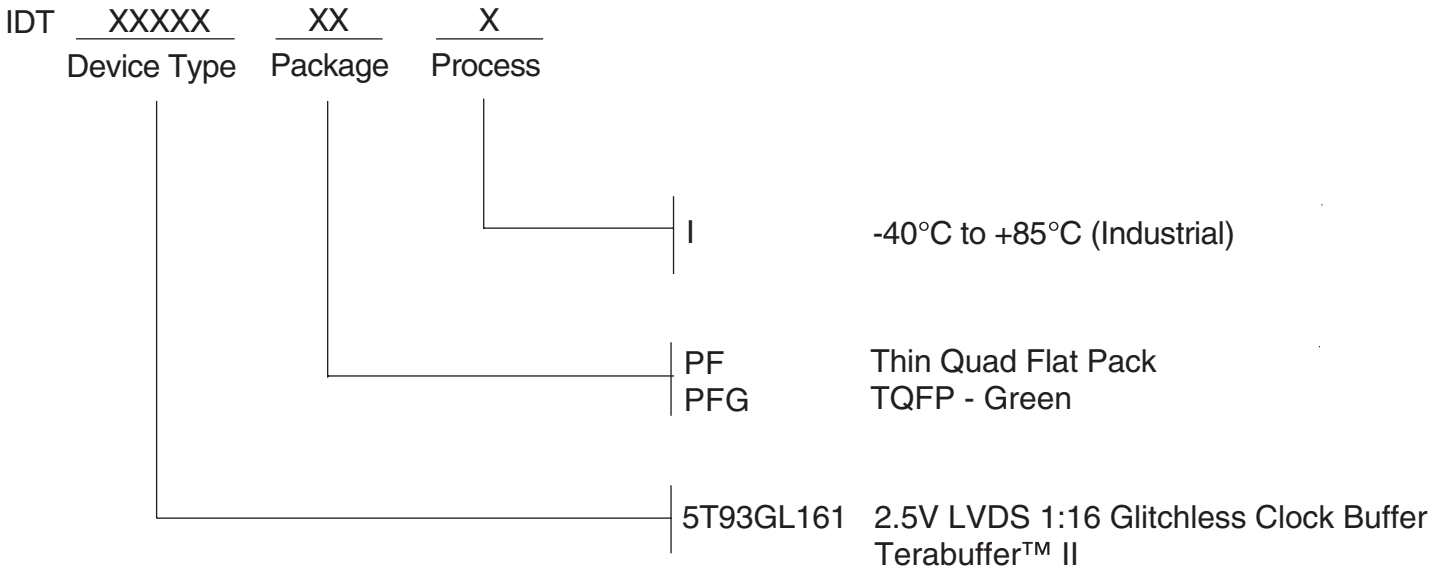
1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M–1982
2. TOP PACKAGE MAY BE SMALLER THAN BOTTOM PACKAGE BY .15 mm
3. DATUMS [A-B] AND [-D-] TO BE DETERMINED AT DATUM PLANE [-H-]
4. DIMENSIONS D AND E ARE TO BE DETERMINED AT SEATING PLANE [-C-]
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS .25 mm PER SIDE. D1 AND E1 ARE MAXIMUM BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH
6. DETAILS OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
7. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
10. ALL DIMENSIONS ARE IN MILLIMETERS
11. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-136, VARIATION BJ AND REGISTRATION MS-026, VARIATION BCB.

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XX± ± XXX± XXXX±	IDT™ www.IDT.com	2975 Stender Way Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674	
APPROVALS	DATE	TITLE PP/PPG PACKAGE OUTLINE 10.0 X 10.0 X 1.4 mm STQFP/TQFP 1.00/.10 FORM	
DRAWN JV	11/18/94		
CHECKED		SIZE C	DRAWING No. PSC-4046 / REV 05
		DO NOT SCALE DRAWING	SHEET 2 OF 2

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
	01	ADDED TABLE FOR 44-PIN	07/05/00	T. VU
	02	CORRECTED P & P1 DIMENSIONS	07/05/00	T. VU
	03	SWAPPED P & P1 DIMENSIONS	08/09/01	D.XUE
	04	ADD STQFP IN THE TITLE BLOCK	08/31/01	
	05	ADD "GREEN" PPG NOMENCLATURE	10/13/04	TU VU

Ordering Information

Table 7. Ordering Information



Revision History Sheet

Rev	Table	Page	Description of Change	Date
A	T3A T3B	4 4 16 17	Added Gate Control Output Table. Added Selection Table. Added Package Outline. Added Package Dimensions. Updated datasheet format.	9/12/08

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